

1A, 200V - 1000V Fast Recovery Surface Mount Rectifier

FEATURES

- AEC-Q101 qualified
- Glass passivated chip junction
- Ideal for automated placement
- Low power loss, high efficiency
- · Fast switching for high efficiency
- Low profile package
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

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AF		LOM		u	4-2

- Freewheeling
- Snubber
- DC/DC converters
- Automotive application

MECHANICAL DATA

- Case: Thin SMA
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: Indicated by cathode band
- Weight: 0.029g (approximately)

KEY PARAMETERS				
PARAMETER	VALUE	UNIT		
l _F	1	Α		
V_{RRM}	200 - 1000	V		
I _{FSM}	30	Α		
T _{J MAX} 150 °		°C		
Package	Thin SMA			
Configuration	Single die			





Thin SMA



ABSOLUTE MAXIMUM RATINGS (T _A = 25°C unless otherwise noted)								
PARAMETER		SYMBOL	RS1D	RS1G	RS1J	RS1K	RS1M	UNIT
			ALH	ALH	ALH	ALH	ALH	
Marking code on the device			RS1DAH	RS1GAH	RS1JAH	RS1KAH	RS1MAH	
Repetitive peak reverse voltage		V_{RRM}	200	400	600	800	1000	V
Reverse voltage, total rms value		$V_{R(RMS)}$	140	280	420	560	700	V
Forward current		I _F	1				Α	
Surge peak forward current, single half sine-wave superimposed on rated load $t = 8.3 \text{ms}$		1	30				Α	
		I _{FSM}	100					Α
Junction temperature		T_J	-55 to +150			°C		
Storage temperature		T _{STG}	-55 to +150			°C		



THERMAL PERFORMANCE					
PARAMETER	SYMBOL	TYP	UNIT		
Junction-to-lead thermal resistance	$R_{\Theta JL}$	19	°C/W		
Junction-to-ambient thermal resistance	$R_{\Theta JA}$	81	°C/W		
Junction-to-case thermal resistance	R _{eJC}	19	°C/W		

Thermal Performance Note: Units mounted on PCB (5mm x 5mm Cu pad test board)

PARAMETE	R	CONDITIONS	SYMBOL	TYP	MAX	UNIT
		$I_F = 0.5A, T_J = 25^{\circ}C$		0.90	-	V
	RS1DALH	I _F = 1.0A, T _J = 25°C		0.97	1.30	V
	RS1GALH RS1JALH	I _F = 0.5A, T _J = 125°C		0.75	-	V
Forward voltage ⁽¹⁾		I _F = 1.0A, T _J = 125°C	.,	0.83	0.94	V
		$I_F = 0.5A, T_J = 25^{\circ}C$	V _F	0.96	-	V
	RS1KALH	I _F = 1.0A, T _J = 25°C		1.04	1.30	V
	RS1MALH	I _F = 0.5A, T _J = 125°C		0.80	-	V
		I _F = 1.0A, T _J = 125°C		0.90	1.11	V
Reverse current @ rated V _R ⁽²⁾		T _J = 25°C		-	1	μA
		T _J = 125°C	- I _R	-	33	μA
	RS1DALH RS1GALH		t _{rr}	-	150	ns
Reverse recovery time	RS1JALH	$I_F = 0.5A, I_R = 1.0A,$ $I_{rr} = 0.25A$		-	250	ns
	RS1KALH RS1MALH	3.237		-	500	ns
Junction capacitance		1MHz, $V_R = 4.0V$	CJ	7	-	pF

Notes:

- 1. Pulse test with PW = 0.3ms
- 2. Pulse test with PW = 30ms

ORDERING INFORMATION				
ORDERING CODE ⁽¹⁾	PACKAGE	PACKING		
RS1xALH	Thin SMA	14,000 / Tape & Reel		

Notes:

1. "x" defines voltage from 200V(RS1DALH) to 1000V(RS1MALH)



CHARACTERISTICS CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$

Fig.1 Forward Current Derating Curve

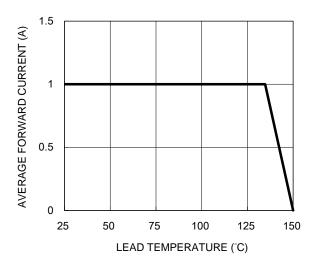


Fig.3 Typical Reverse Characteristics

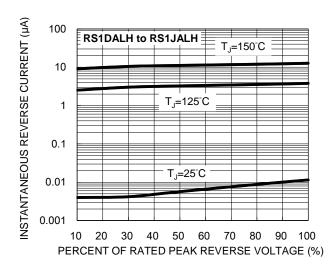


Fig.5 Typical Reverse Characteristics

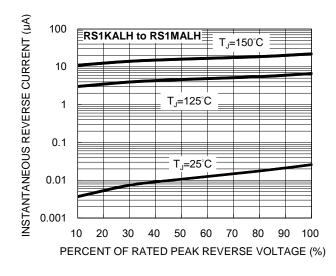


Fig.2 Typical Junction Capacitance

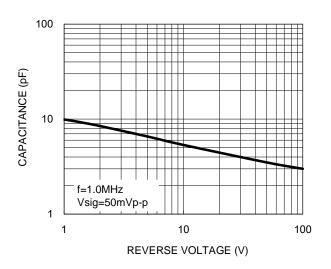


Fig.4 Typical Forward Characteristics

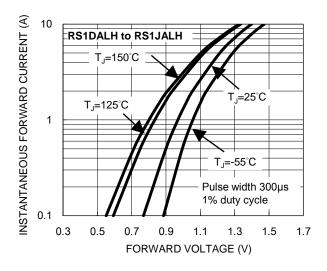
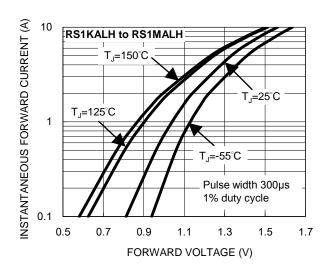


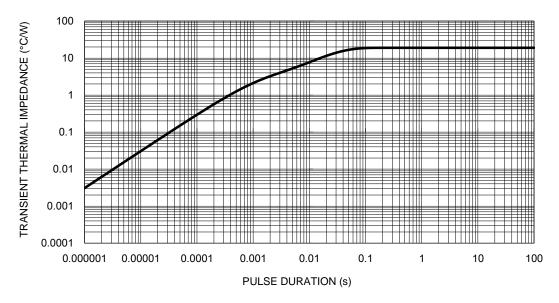
Fig.6 Typical Forward Characteristics



CHARACTERISTICS CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$

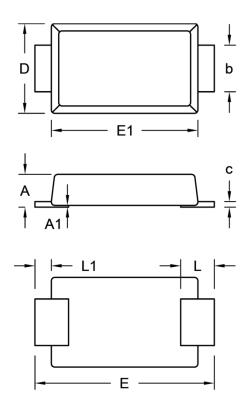
Fig.7 Typical Transient Thermal Impedance





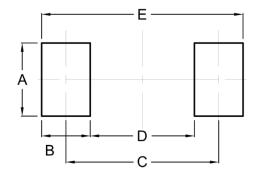
PACKAGE OUTLINE DIMENSIONS

Thin SMA



DIM.	Unit (mm)		Unit (inch)	
Dilvi.	Min.	Max.	Min.	Max.
Α	0.90	1.00	0.035	0.039
A1	0.00	0.10	0.000	0.004
b	1.25	1.45	0.049	0.057
С	0.10	0.22	0.004	0.009
D	2.50	2.70	0.098	0.106
E	5.05	5.35	0.199	0.211
E1	4.15	4.35	0.163	0.171
L	0.75	1.20	0.030	0.047
L1	0.30	0.60	0.012	0.024

SUGGESTED PAD LAYOUT



Symbol	Unit (mm)	Unit (inch)
Α	2.10	0.083
В	1.40	0.055
С	4.40	0.173
D	3.00	0.118
E	5.80	0.228

MARKING DIAGRAM



P/N = Marking Code YW = Date Code F = Factory Code



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